Special Issue

Flexible and Biodegradable Electronics and Novel Semiconductor Devices

Message from the Guest Editor

Continuous innovation in electronics requires flexible, biocompatible, sustainable, and high-performance materials and devices, and the rapid advancement of flexible and biodegradable electronics is revolutionizing healthcare, wearable technology, and sustainable electronics. Innovations in semiconductor materials and fabrication techniques are at the heart of this progress. This special issue highlights breakthroughs in flexible hybrid electronics (FHE), biodegradable materials, and novel semiconductor architectures to address challenges in healthcare, wearable technology. environmental sustainability, and next-generation computing. Interdisciplinary research results from leading institutions around the world showcase key advances in material design, fabrication techniques, and multifunctional applications.

Guest Editor

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